506825073 08/18/2021

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TADAYUKI ITO	07/14/2021
TAKESHI SASAKI	07/14/2021

RECEIVING PARTY DATA

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City:	ITABASHI-KU, TOKYO	
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17445399

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NAME OF SUBMITTER:	DIKLA BOROCHOV	
SIGNATURE:	/Dikla Borochov/	
DATE SIGNED:	08/18/2021	

Total Attachments: 3

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> **PATENT** REEL: 057220 FRAME: 0731

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ASSIGNMENT AND AGREEMENT

For value received, I, Tadayuki ITO of Itabashi-ku, Tokyo, Japan; and Takeshi SASAKI of Itabashi-ku, Tokyo, Japan hereby sell, assign and transfer to TOPCON CORPORATION, a corporation of the Country of Japan, having a business address at 75-1, Hasunuma-cho, Itabashi-ku, Tokyo 174-8580. Japan, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to DATA PROCESSING, DATA PROCESSING METHOD, AND DATA PROCESSING PROGRAM, described in an application for Letters Patent of the United States, claiming priority to Japanese Patent Application No. 2020-147407 filed September 2, 2020, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United States for said inventions; and I also concurrently hereby sell, assign and transfer to TOPCON CORPORATION the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

I authorize **TOPCON CORPORATION** to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from me, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of **TOPCON CORPORATION** to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

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I request that any and all patents for said inventions be issued to **TOPCON CORPORATION** in the United States and in all countries foreign to the United States, or to such nominees as **TOPCON CORPORATION** may designate.

I agree that, when requested, we shall, without charge to **TOPCON CORPORATION** but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor(s) Signature:	
Tadayakid Oto	<u>July 14th , 2021</u>
Tadayuki ITO	Date
Janadon	July 14th, 2021
Witness Signature	Date
Mitsuharu YAMADA	

Print name of witness

Inventor(s) Signature:	
Zopeshi Sarahi Takeshi SASAKI	July 14th, 2021
Takeshi SASAKI	Date
Witness Signature	<u>July 14th, 2021</u> Date
Mitsuharu YAMADA Print name of witness	